



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20180531005
Datasheet for PCM1860- PCM1865
Information Only**

Date: June 01, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is information-only announcement of a change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
PCM1862DBT	null
PCM1860DBT	null
PCM1861DBT	null
PCM1863DBT	null
PCM1864DBT	null
PCM1865DBT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180531005	PCN Date:	June 1, 2018
Title:	Datasheet for PCM1860- PCM1865		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**PCM1860, PCM1861, PCM1862
PCM1863, PCM1864, PCM1865**

SLAS831D – MARCH 2014 – REVISED MARCH 2018

Changes from Revision C (August 2014) to Revision D

Page

• Added PCM1860, PCM1862, and PCM1864 and related content to this data sheet; these devices were previously in a separate data sheet (SLASE55A)	1
• Changed title for clarity	1
• Changed <i>Feature</i> bullets to include new devices	1
• Added <i>Feature</i> bullets to clarify hardware- and software-controlled devices	1
• Changed <i>Application</i> from "Automotive Head Units" to "Voice Controlled Devices"	1
• Changed <i>Description</i> section text to clarify 3.3-V supply, integrated PGA, and additional front-end features	1
• Changed <i>Simplified Application Diagram</i> to combine two previous figures into one figure	1
• Deleted <i>Typ Performance (3.3-V Supply, -1 dB-FS Input)</i> table; redundant content	7
• Changed <i>Device Comparison Table</i> ; updated for clarity	7
• Changed reference voltage output dcoupling point typical value from 0.5 VCC to 0.5 AVDD in VREF pin description	9
• Changed XO (pin 9) type from "—" to "Digital output" in both <i>Pin Functions</i> tables	9
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• Deleted all rows with Powerdown; not a valid operating mode	14
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- Changed *Digital Audio Output 2 Configuration* section; DOUT2 not available in TDM mode, only for 4-ch devices 58
- Added *Time Division Multiplex (TDM Support)* section 58
- Changed location of timing diagrams to *Specifications* section, and deleted *Interface Timing* section 59
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- Added text "The I²C control port.." to the *I²C Interface* section 64
- Changed pin numbers in Table 22 from "15, 16, 14" to "23, 24, 25" 64
- Added *Real World Software Configuration using EnergySense and Controlsense* section 65
- Added more detail to *Programming DSP Coefficients on Software-Controlled Devices* section, and moved to new location 68
- Added *Dual PCM186x TDM Functionality* section 73
- Added new paragraph to end of *Analog Front-End Circuit For Single-Ended, Line-In Applications* section 74
- Changed *1.8-V Support* section; clarified that both IOVDD and LDO must be driven with 1.8 V in 1.8-V mode 79
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- Deleted old Figure 67, *PCM1865 EVM Signal Partitioning*; redundant, and same information shown in Figure 74 84
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- Changed default values in page 1: register 1 for bits 4, 2, 1, and 0 from "1" to "0", and updated descriptions for clarity. 129

The datasheet number will be changing.

Device Family	Change From:	Change To:
PCM1860- PCM1865	SLVS893C	SLVS893D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/PCM1860>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

PCM1860DBT	PCM1860DBTR	PCM1861DBT	PCM1861DBTR
PCM1862DBT	PCM1862DBTR	PCM1863DBT	PCM1863DBTR
PCM1864DBT	PCM1864DBTR	PCM1865DBT	PCM1865DBTR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com